

TG3010I

Thermal Silicone Grease

BENEFITS AND FEATURES

- Low viscosity and excellent thixotropy for dispensing, stencil printing, or screen printing
- Low bond line thickness providing low thermal impedance
- Excellent electric insulation with ceramic filler ;
- High stability and reliability
- Stable homogeneous mixture under room temperature storage

OVERVIEW

Honeywell TG3010I Thermal Silicone Grease product provides superior thermal performance with ease of use across multitude of applications. Its low viscosity and excellent thixotropy enable it fit for large-scale production with dispensing, screen printing and stencil printing. It is designed to minimize thermal resistance at interfaces, and maintain excellent performance through reliability testing.



TYPICAL APPLICATIONS

- CPU, GPU and chipsets
- LED assemblies
- Automotive electronics
- IGBT & power units
- Flip-chip BGAs

STORAGE & USE

- Shelf Life 12 months at 20-35 °C
<65%RH

Property		TG3010I	Test Method
Color		White	-
Specific Gravity		3.4	ASTM D792
Viscosity	cps@25°C	200,000	BrookfieldViscometer
	Pa.s@25°C	450	Share rate 10 1/s @25°C
Thermal Conductivity (W/m·K)		3.0	Hot Disk
Thermal Impedance (°C·in ² /W) (35psi, 50°C)		0.005	ASTM D5470
BLT(um) (35psi, 50°C)		10	HON Internal
Volume Resistivity (ohm·cm)		2.0 x 10 ¹²	ASTM D257
Dielectric Constant (@ 1MHz)		>5	ASTM D150
Flammability Rating		V-0	UL 94
Working Temperature (°C)		-40-150	-

Honeywell Electronic Materials

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